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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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LIM ET AL	
SERIAL NO. 10 520 842	Art Unit: 1714
FILED: JANUARY 10 2005	Examiner: TO BE ASSIGNED
FOR: FLAME RETARDANT) THERMOPLASTIC RESIN COMPOSITION)	Docket No.: DKC 1755
Commissioner for Patents Alexandria, VA 22313	

INFORMATION DISCLOSURE STATEMENT

Sir:

Enclosed is a copy of a non-U.S. patent reference for consideration by the Examiner and a PTO Form 1449 listing the reference. The Examiner is respectfully requested to consider the reference listed on the Form 1449 and return an initialed copy of the Form 1449 to Applicants.

No Office action has been mailed so no fee is due.

Respectfully submitted,

LIM ET AL

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313 on October 17, 2005

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U.S. Department of Commerce

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

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	DKC	1755

SERIAL NO.:

10 520 842

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FILING DATE:

GROUP:

January 10, 2005

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U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
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FOREIGN PATENT DOCUMENTS

EXAMINER	DOCUMENT NUMBER	DATE	COLDITAN	GT A GG	CLID CL A CC	TRANSLATION	
INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
	WO 02 46287	6/13/2002	PCT				Х
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EXAMINER INITIALS	OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)				
	Abstract of WIPO Publication No. WO 02 46287, June 13, 2002				
EXAMINER	DATE CONSIDERED				
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in					

conformance and not considered. Include copy of this form with next communication to applicant.